ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN22189X
Issue Date: 9 May 2019

Title of Change:	Memory Products US8 Back End Site and Material Change.
Proposed first ship date:	16 August 2019
Contact information:	Contact your local ON Semiconductor Sales Office or <logic.fpcn@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Phine.Guevarra@onsemi.com>.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>
Change Part Identification:	Affected product will be marked with new marking style
Change Category:	☐ Wafer Fab Change ☑ Assembly Change ☑ Test Change ☐ Other ________

Change Sub-Category(s):

☐ Manufacturing Site Addition
☑ Manufacturing Site Transfer
☑ Manufacturing Process Change

☑ Material Change
☐ Product specific change

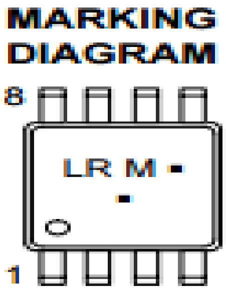
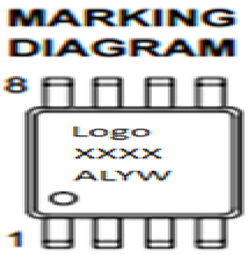
☐ Datasheet/Product Doc change
☑ Shipping/Packaging/Marking
☐ Other: ____________

Sites Affected:	ON Semiconductor Sites: ON Seremban, Malaysia	External Foundry/Subcon Sites: Subcon Thailand

Description and Purpose:

Qualify and transfer to a new subcon site to increase capacity.

Material to be changed	Before Change (Existing flow)	After Change (new flow)
Assy Site	ON Seremban Malaysia	Subcon Thailand
Mold Compound	MC SUMITOMO EME-G600FB	Molding Compound G600
Lead frame	AG STRIPE OVER D005	LF; PPF+ME2; US8; DAP 59x38
Die Attach	DA EN4370K3 SNAP CURE NON-C	Non-Conductive DAF, HR-5140
Plating	100% Sn	Preplated

	From	To
Product marking change	 LR =Device Code, M = D ate Code, Dot(.)=Lead Free Package	 XXXX=Device Code, A= Assy location, L= Lot Code,Y=Year Code, W =Week Code

Reliability Data Summary:

QV DEVICE NAME: N24C64UVTG
RMS: S44275, S51871, S51869, I51156 and I48941
PACKAGE: US 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C	1008 hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/80
TC	JESD22-A104	Ta= -65°C to + 150°C	1000 cyc	0/80
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/80
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/80
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		0/240
SD	JSTD002	Ta = 245C, 10 sec		0/ 15
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30

Electrical Characteristic Summary:

No impact on electrical characteristic.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal.**

Part Number	Qualification Vehicle
N24C08UDTG	N24C64UVTG
N24C02UDTG	
N24C64UDTG	
N24C16UDTG	
N24C32UDTG	